

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KAIZHOU TAN	07/05/2018
GANGYI HU	07/05/2018
ZHAOHUAN TANG	07/06/2018
JIANAN WANG	07/06/2018
YONGHUI YANG	07/06/2018
YI ZHONG	07/06/2018
YANG CAO	07/06/2018
YONG LIU	07/06/2018
KUNFENG ZHU	07/06/2018
RECEIVING PARTY DATA	
Name:	NO. 24 RESEARCH INSTITUTE OF CHINA ELECTRONICS TECHNOLOGY GROUP CORPORATION
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State/Country:	CHINA
Postal Code:	400060
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16068098
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DATE SIGNED:	09/19/2018
Total Attachments: 1 source=GUH-370ASSIGN#page1.tif	

ASSIGNMENT

GUH-370US

WHEREAS, I/WE:

TAN, Kaizhou; HU, Gangyi; TANG, Zhaohuan; WANG, Jian' an; YANG, Yonghui;
ZHONG, Yi; CAO, Yang; LIU, Yong; ZHU, Kunfeng, residing in
NO.14 Huayuan Road Nanping, Nan'an District, Chongqing-400060, China
have invented certain new and useful improvements in the following:

SEMICONDUCTOR CELL STRUCTURE AND POWER SEMICONDUCTOR DEVICE
for which a United States patent application therefor has been executed on _____, U.S. Patent
Application No.: 16068098;

WHEREAS,

NO.24 RESEARCH INSTITUTE OF CHINA ELECTRONICS
TECHNOLOGY GROUP CORPORATION

(hereinafter referred to as the Assignee), residing at NO.14 Huayuan Road Nanping, Nan'an District,
Chongqing-400060, China desires to acquire the entire right, title and interest in said application and
invention, and to any United States and foreign patents to be obtained therefor.

NOW THEREFORE, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the
above named, hereby sell, assign, and transfer to Assignee, its successors and assigns, the entire right,
title and interest in said application and inventions therein disclosed for the United States and foreign
countries, and all rights of priority resulting from the filing of said application, I/we hereby agree that
Assignee may apply for foreign Letters Patent on said inventions, and I/we hereby agree to timely
execute all papers necessary in connection with said United States and foreign Letters Patent
applications when called upon to do so by Assignee.

I/we hereby covenant that I/we have the full and lawful right to convey the entire right, title, and
interest herein assigned, and that I/we have not entered and will not enter into any agreement in
conflict herewith.

I/we hereby request the Commissioner for Patents to issue any Letters Patent granted upon the
inventions set forth in said application to Assignee, its successors and assigns.

ASSIGNOR SIGNATURE(S)

<u>TAN, Kai zhou</u> TAN, Kaizhou	<u>2018.7.5</u> Date	<u>HU, Gangyi</u> HU, Gangyi	<u>2018.7.5</u> Date
<u>Tang, zhaohuan</u> TANG, Zhaohuan	<u>2018.7.6</u> Date	<u>Wang jian'an</u> WANG, Jian' an	<u>2018.7.6</u> Date
<u>YANG, Yonghui</u> YANG, Yonghui	<u>2018.7.6</u> Date	<u>Zhong Yi</u> ZHONG, Yi	<u>2018.7.6</u> Date
<u>CAO, Yang</u> CAO, Yang	<u>2018.7.6</u> Date	<u>Liu Yong</u> LIU, Yong	<u>2018.7.6</u> Date
<u>Zhu, kunfeng</u> ZHU, Kunfeng	<u>2018.7.6</u> Date		